

PRODUCTS APPLICATIONS DESIGN SUPPORT SAMPLE AND BUY ABOUT US CONTACT US MYMICROCHIP LOGIN

more...

Product Change Notification - RMES-02QYDW424 (Printer Friendly)

Date:

18 Apr 2017

Product Category:

Power Management - System Supervisors/Voltage Detectors; Linear Regulators

Notification subject:

CCB 2885 Initial Notice: Qualification of JCET as an additional assembly site for selected products of the 120K wafer technology available in 3L SOT-23 package using (CuPdAu) bond wire.

Notification text:

PCN Status:

Initial notification.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN # Affected CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of JCET as an additional assembly site for selected products of the 120K wafer technology available in 3L SOT-23 package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at MTAI, ATES or NSEB using gold (Au) bond wire and G600 molding compound material.

Post Change:

Assembled at MTAI, ATES and NSEB using gold (Au) bond wire and G600 molding compound material or assembled at JCET using palladium coated copper with gold flash (CuPdAu) bond wire and ELER-8-100HFE molding compound material.

Pre and Post Change Summary:

		Pre Change		Post Change					
Assembly Site	MTAI	ATES	NSEB	MTAI	ATES	NSEB	JCET		
Lead frame material	CDA194	CDA194	CDA194	CDA194	CDA194	CDA194	CDA194		
Wire material	Au	Au	Au	Au	Au	Au	CuPdAu		
Die attach material	84-3J/ 8006NS	2025DSI	8006NS	84-3J/ 8006NS	2025DSI	8006NS	8006NS		
Mold compound material	G600	G600	G600	G600	G600	G600	ELER-8- 100HFE		

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying JCET as an additional assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

June 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	April 2017			^	June 2017				
Workweek	14	15	16	17		23	24	25	26
Initial PCN Issue Date			Х						
Qual Report Availability									X
Final PCN Issue Date									X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

April 18, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_RMES-02QYDW424_Qual_Plan.pdf PCN_RMES-02QYDW424_Affected_CPN.pdf PCN_RMES-02QYDW424_Affected_CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."













Products | Applications | Design Support | Training | Sample And Buy | About Us | Contact Us | Legal | Investors | Careers | Support

©Copyright 1998-2017 Microchip Technology Inc. All rights reserved.